
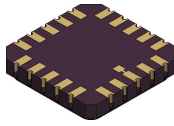


# DATA BOOK PACKAGE OUTLINE

DRAFTER: K. SINCERBOX	DATE: 01/13/2023		DIMENSIONS IN MILLIMETERS			
DESIGNER:	DATE:	 <b>TEXAS INSTRUMENTS</b> SEMICONDUCTOR OPERATIONS		CODE IDENTITY NUMBER 01295		
CHECKER: K. SINCERBOX	DATE: 01/13/2023					
ENGINEER: D. CHIN	DATE: 01/13/2023	<b>ePOD, FK0020A / LCCC, 20 PIN, 1.27 MM PITCH</b>				
APPROVED: D. CHIN	DATE: 01/13/2023					
RELEASED: K. SINCERBOX	DATE: 01/13/2023					
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	SCALE NTS	SIZE A	4219737	REV A	PAGE 1 OF 5

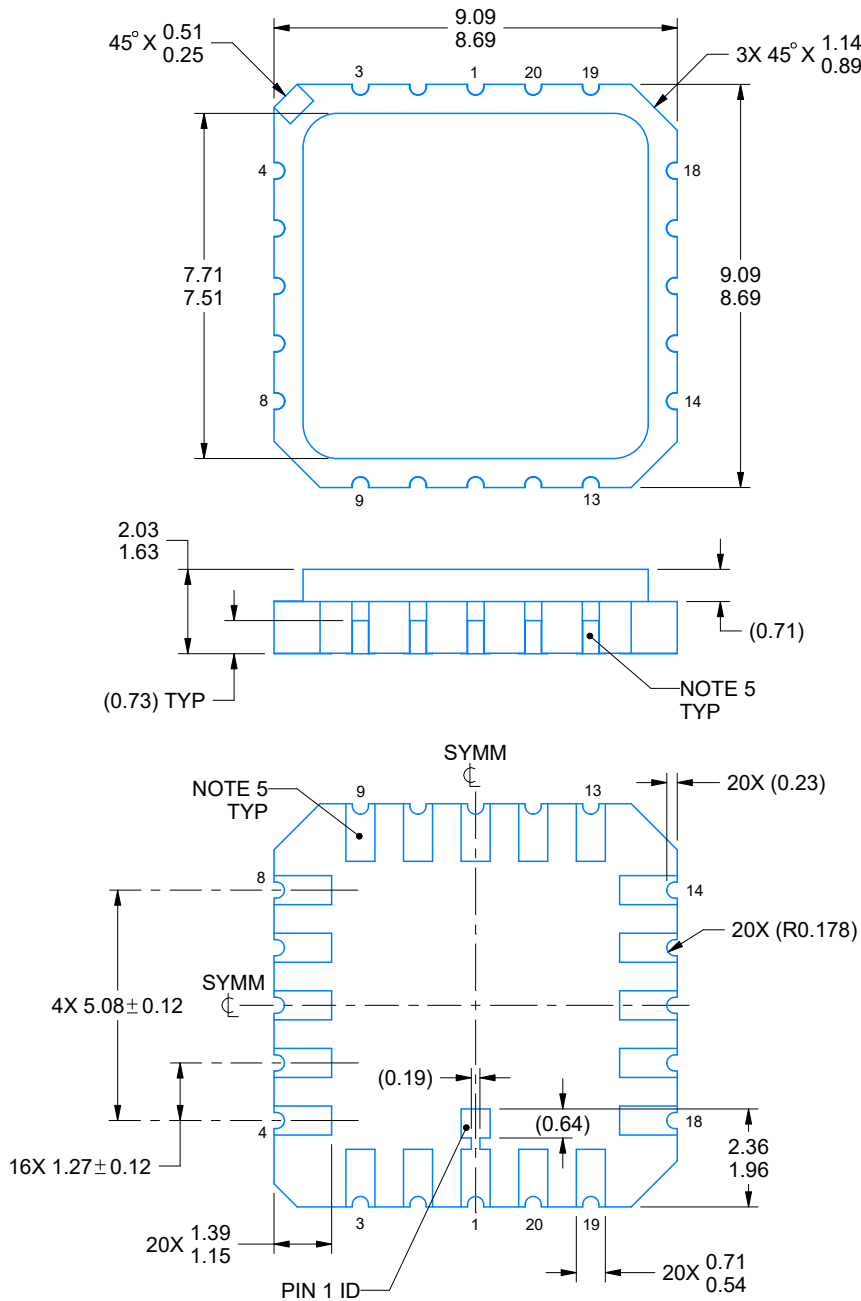


**FK0020A**

**PACKAGE OUTLINE**

**LCCC - 2.03 mm max height**

LEADLESS CERAMIC CHIP CARRIER



4219737/A 01/2023

**NOTES:**

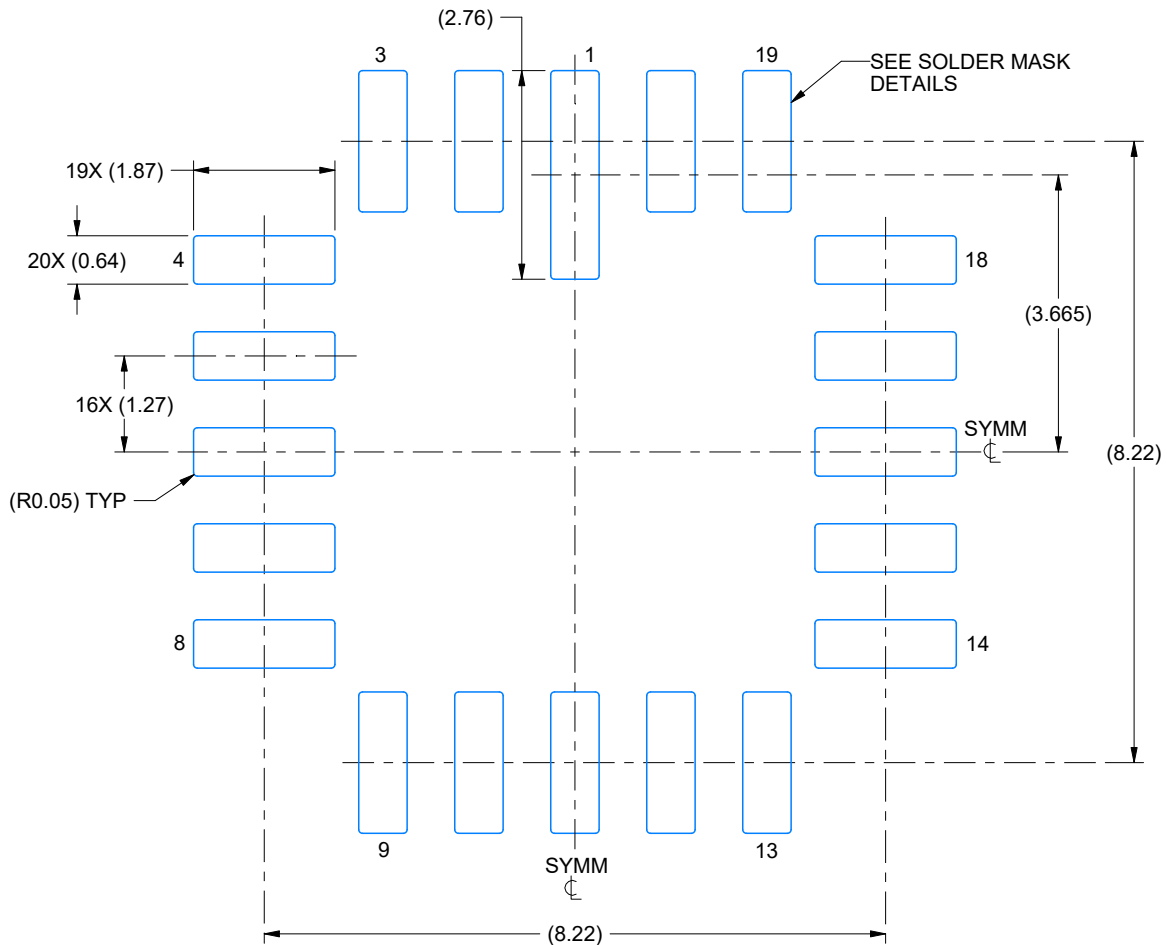
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package can be hermetically sealed with a metal lid.
4. Reference JEDEC Registration MS-004.
5. The terminals are gold-plated.

# EXAMPLE BOARD LAYOUT

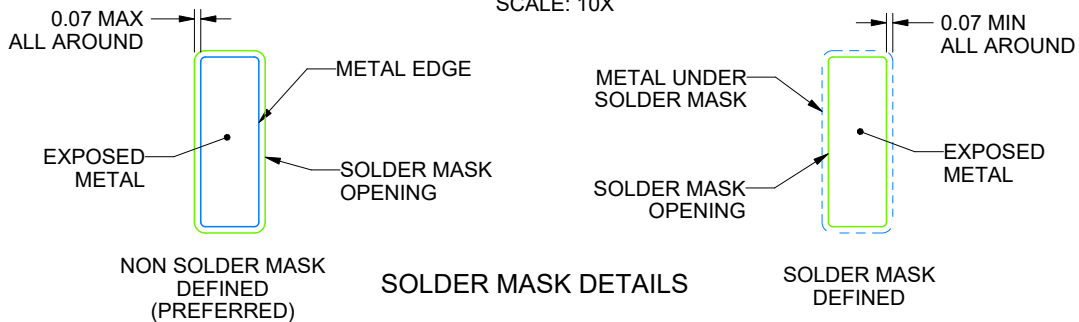
FK0020A

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4219737/A 01/2023

NOTES: (continued)

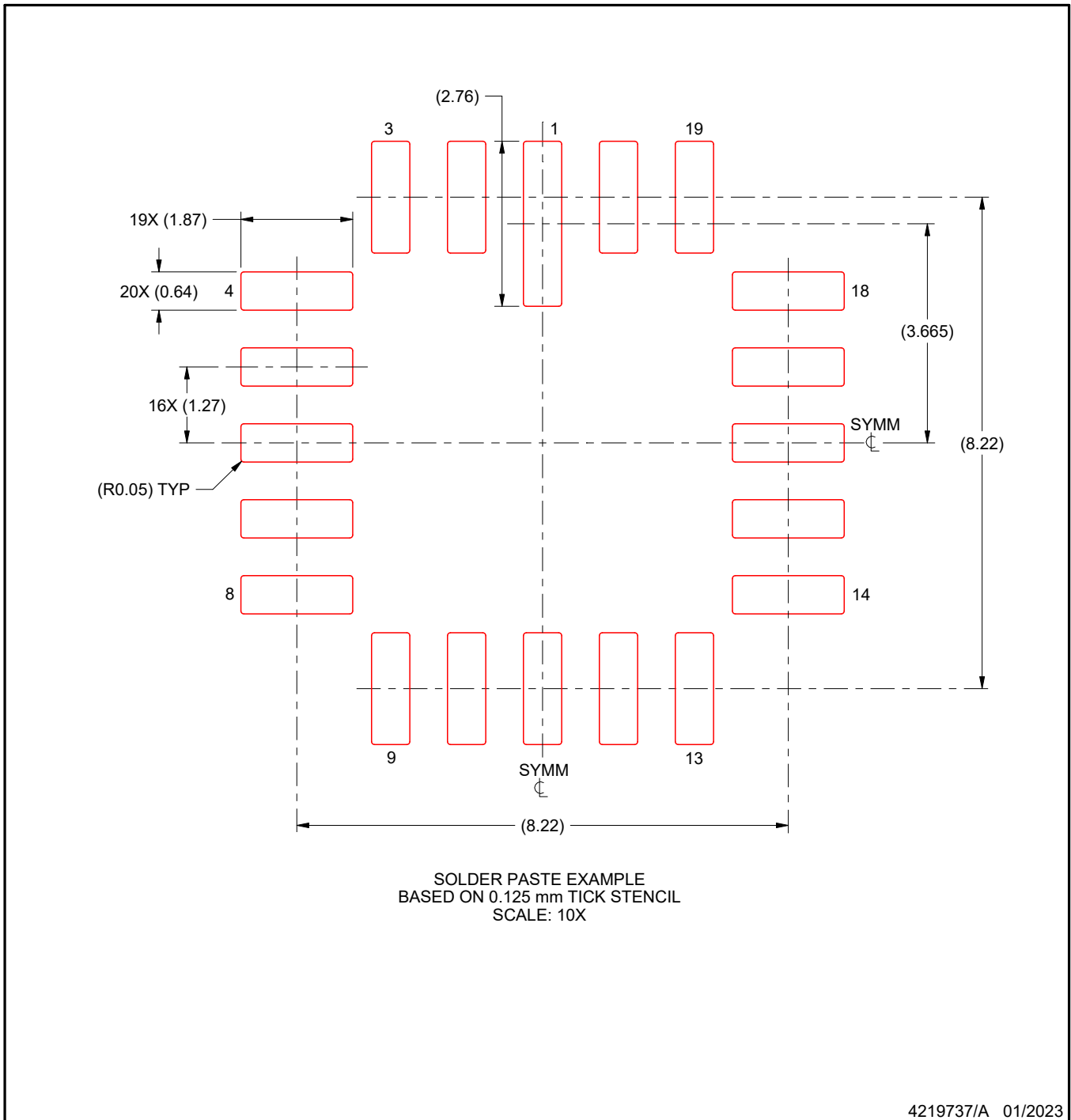
6. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

FK0020A

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2202771	01/13/2023	D. CHIN / K. SINCERBOX